

TECH	INICAL DATA SH	IEET	2/4
MALE STRAIGHT RECEPTACLE FOR PCB			R222.428.700
PIN IN PASTE - SM	Series : SMP		
PACKAGING		<b>SPECIFICATION</b>	
Standard     Unit       100     'W' option	Other Contact us		
ELECTRICAL CHARACTERISTICS		<b>ENVIRONMENTAL</b>	
VSWR 1.15* + 0,0000 Insertion loss 0.12 RF leakage - ( NA Voltage rating 335 Dielectric withstanding voltage 500	GHz	Operating tempe Hermetic seal Panel leakage	orature -65/+165 ° C NA Atm.cm3/s NA
		OTHERS CHARACTERISTICS	
Axial force – Opposite end6.8TorqueRecommended torque	RISTICS N mini N mini N.cm mini N.cm	Assembly instruction Others : Compliant with MIL-STD-348 *At 12.4GHz - Performance strongly depends on lay out and PCB material	
6	N.cm		
Mating life1000Weight0,3500	Cycles mini g		
<b>Issue :</b> 0914 C In the effort to improve our products, we reserve	e the right to make ch	anges judged to be	

#### TECHNICAL DATA SHEET

## MALE STRAIGHT RECEPTACLE FOR PCB

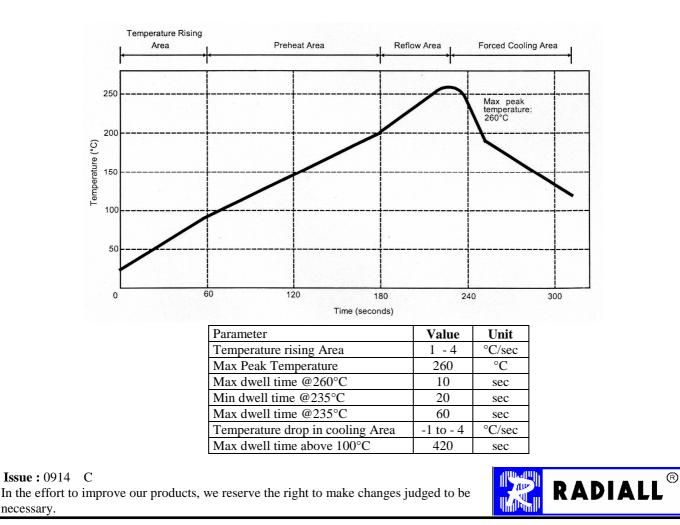
### PIN IN PASTE - SMOOTH BORE

Series : SMP

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# SOLDER PROCEDURE

- Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microns (5.85 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
  Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.



#### TEMPERATURE PROFILE

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#### TECHNICAL DATA SHEET

### MALE STRAIGHT RECEPTACLE FOR PCB

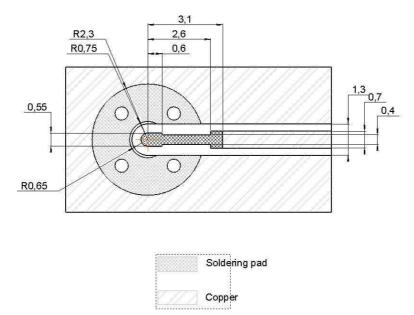
### **PIN IN PASTE - SMOOTH BORE**

Series : SMP

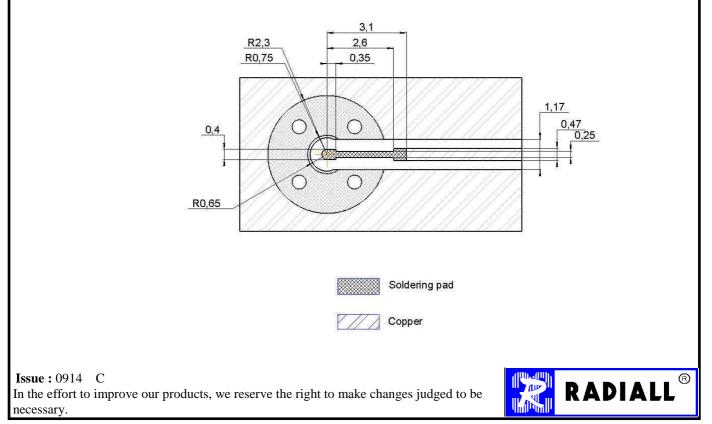
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## **RECOMMENDED PAD DIMENSIONS:**

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides : Add vias between both sides along upper ground plane according to engineering practise



Substrate: RO4350 thickness 0.254mm, with copper layer  $35\mu m$  on both sides : Add vias between both sides along upper ground plane according to engineering practise



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